RELIABILITY REPORT

FOR

MAX9315EUP

PLASTIC ENCAPSULATED DEVICES

June 18, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

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Conclusion

The MAX9315EUP successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX9315 low-skew, 1-to-5 differential driver is designed for clock and data distribution. This device allows selection between two inputs. The selected input is reproduced at five differential outputs. The differential inputs can be adapted to accept a single-ended input by connecting the on-chip VBB supply to one input as a reference voltage. The MAX9315 features low output-to-output skew (20ps), making it ideal for clock and data distribution across a backplane or a board. For interfacing to differential HSTL and LVPECL signals, this device operates over a +2.375V to +3.8V supply range, allowing high-performance clock or data distribution in systems with a nominal +2.5V or +3.3V supply. For differential LVECL operation, this device operates with a -2.375V to -3.8V supply. The MAX9315 is offered in a space-saving 20-pin TSSOP package.

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II. Manufacturing Information

A. Description/Function:	1:5 Differential LVPECL/LVECL/HSTL Clock and Data Driver
B. Process:	GST2
C. Number of Device Transistors:	616
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Malaysia
F. Date of Initial Production:	October 27, 2001

III. Packaging Information

A. Package Type:	20-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	85Sn/15Pb
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3601-0018
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	91°C/W
K. Single Layer Theta Jc:	20°C/W
L. Multi Layer Theta Ja:	73.8°C/W
M. Multi Layer Theta Jc:	20°C/W

IV. Die Information

A. Dimensions:	79 X 46 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Poly / Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 140 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 10.93 \times 10^{-9}$

λ = 10.93 F.I.T. (60% confidence level @ 25°C)

This following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliabilty Report found at http://www.maxim-ic.com/. Current monitor data for the GST2 Process results in a FIT Rate of 0.08 @ 25C and 1.42 @ 55C (0.8 eV, 60% UCL).

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The EC14 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

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Table 1
Reliability Evaluation Test Results

MAX9315EUP

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

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